



PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 22, 2004
Date

T. Miller
Tamra Miller

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/631,342	Confirmation No. : Not yet assigned
Applicants : Sion C. Quinlan and Tim J. Bales	
Filed : July 30, 2003	Attorney Docket No.: 30022/US/2 (500986.03)
Art Unit : Not yet assigned	Customer No. : 27,076
Examiner : Not yet assigned	
Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND METHOD FOR ELECTRICALLY ISOLATING MODULES	

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicants wish to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449. Copies of the cited foreign patent and non-patent literature references, as required under 37 C.F.R. § 1.98(a)(2), are enclosed. Copies of the cited U.S. patents and U.S. patent application publications will not be submitted herewith in accordance with the waiver by the Office of the requirement under 37 C.F.R. § 1.98(a)(2)(i) for U.S. national patent applications filed after June 30, 2003. Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicants' duty to disclose all information they are aware of which is believed relevant to the examination of the above-identified application, applicants believe that their invention is patentable.

I hereby certify that no item set forth on the attached form PTO-1449 was cited in a communication from a foreign patent office in a counterpart foreign application or, to my knowledge, after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of this Information Disclosure Statement.

Please acknowledge receipt of this Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted,

DORSEY & WHITNEY LLP



Steven H. Arterberry
Registration No. 46,314

SHA:tlm

Enclosures:

Postcard
Form PTO-1449
Cited References (2)

1420 Fifth Avenue, Suite 3400
Seattle, WA 98101
Telephone (206) 903-8800
Facsimile (206) 903-8820

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FORM PTO-1449
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
30022/US/2 (500986.03)APPLICATION NO.
10/631,342

INFORMATIONAL DISCLOSURE STATEMENT

(Use several sheets if necessary)

APPLICANT(S)

Sion C. Quinlan and Tim J. Bales

FILING DATE

July 30, 2003

GROUP ART UNIT

Not yet assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,027,253	06/25/91	Lauffer et al.	361	321	
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AK							
	AL							
	AM							
	AN							
	AO							

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	AP	IBM Technical Disclosure Bulletin NN8712167, "Decoupling Capacitor Structure to Reduce FET Output Driver Switching Noise", December 1, 1987, pages 167-168.
	AQ	IBM Technical Bulletin NN85014857, "Clipped Decoupled Twin-Carrier Module for IC Memory Chips", January 1, 1985, page numbers 4857-4858.

EXAMINER

DATE CONSIDERED

* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).